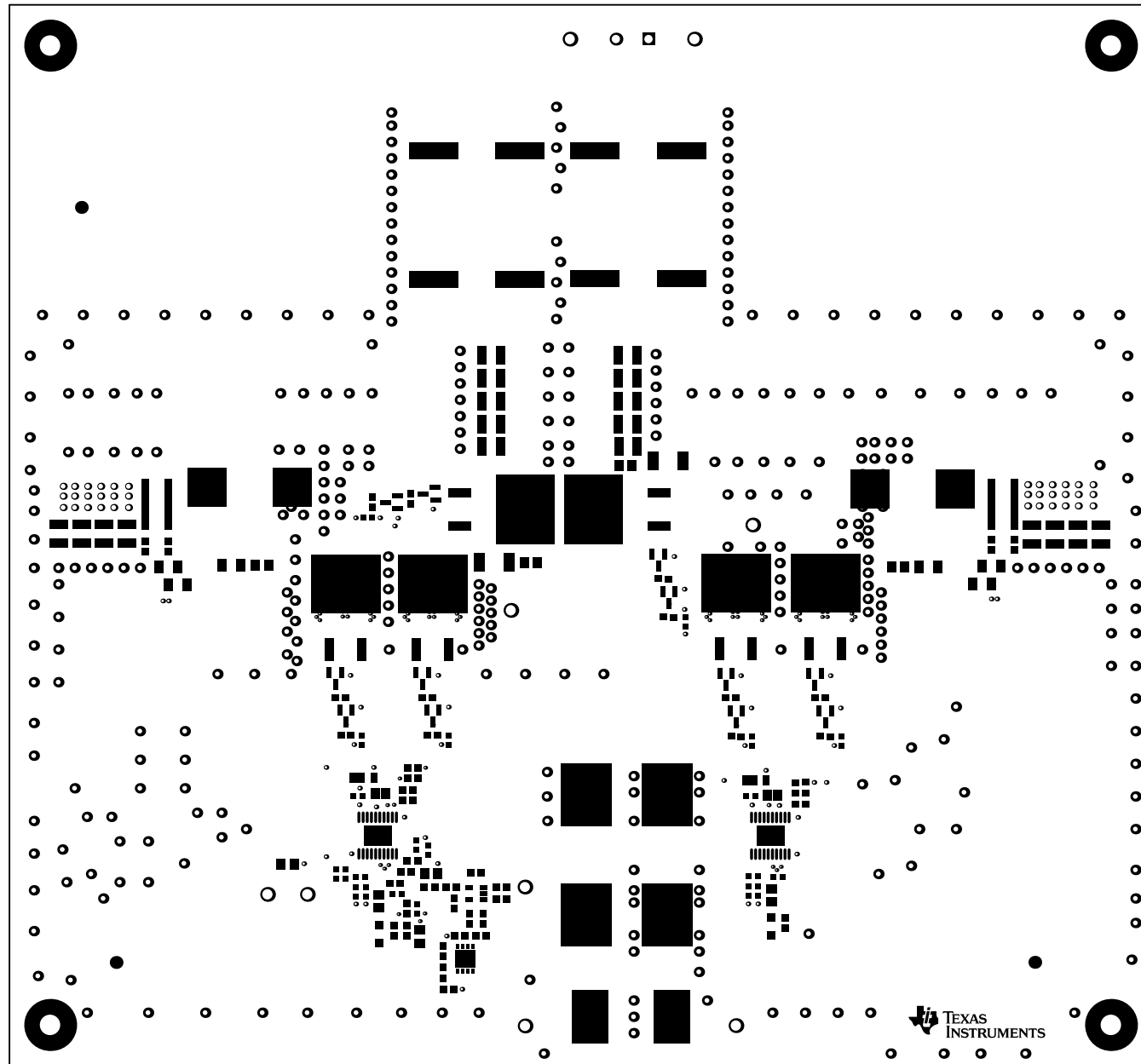
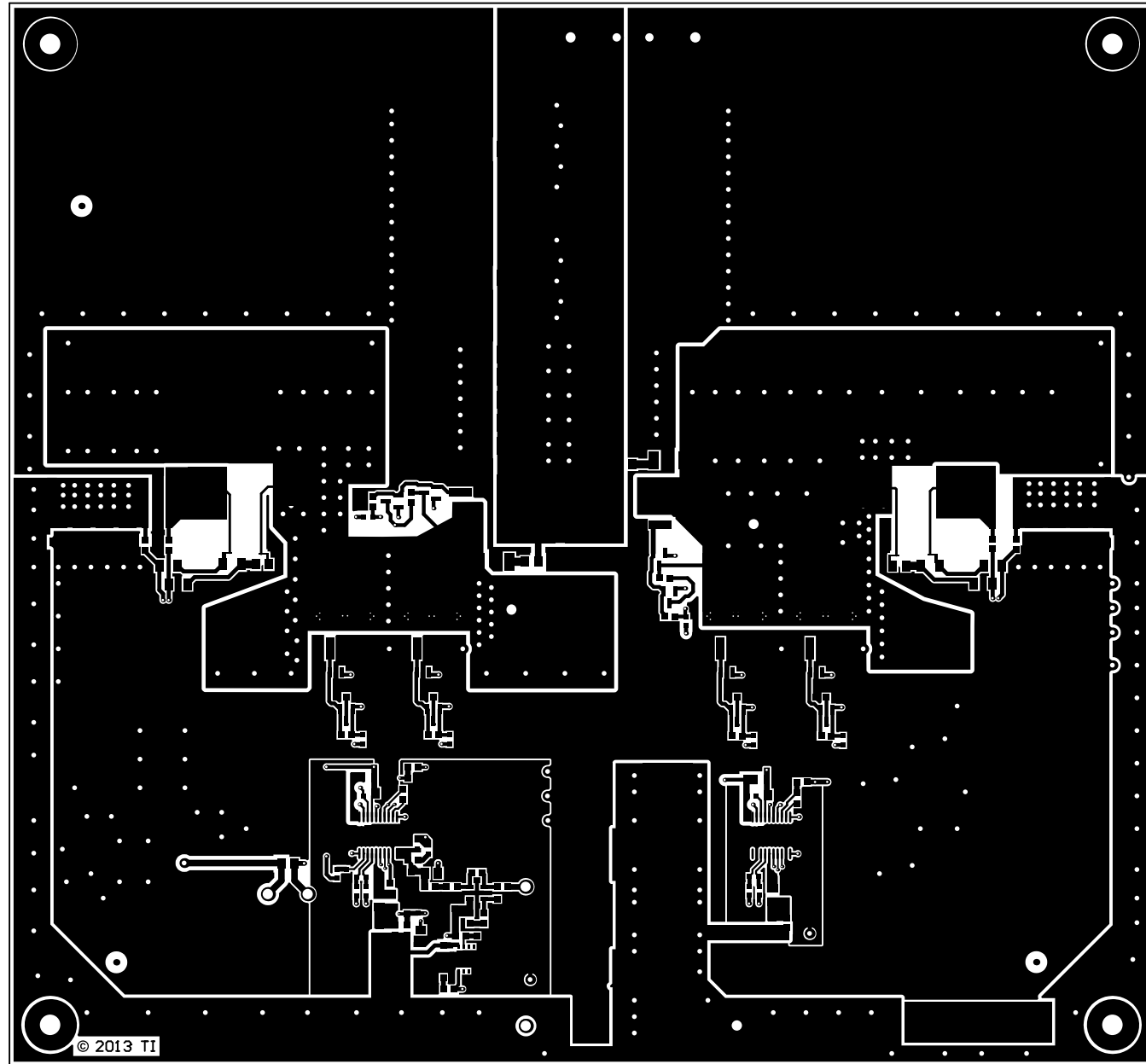


Z22

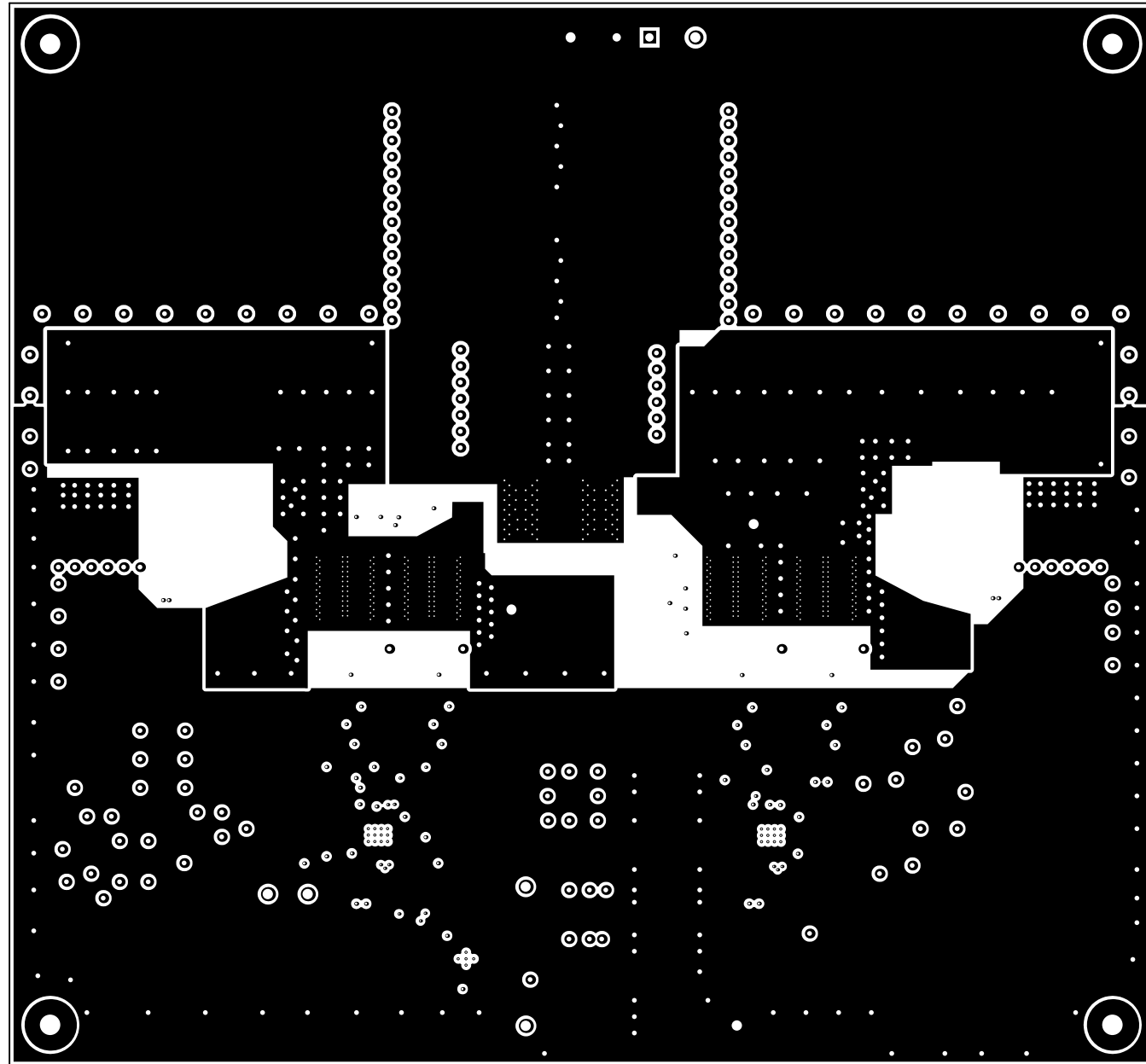
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Top Overlay		
PLOT NAME = Top Overlay	GENERATED : 9/23/2015 2:04:17 PM	TEXAS INSTRUMENTS



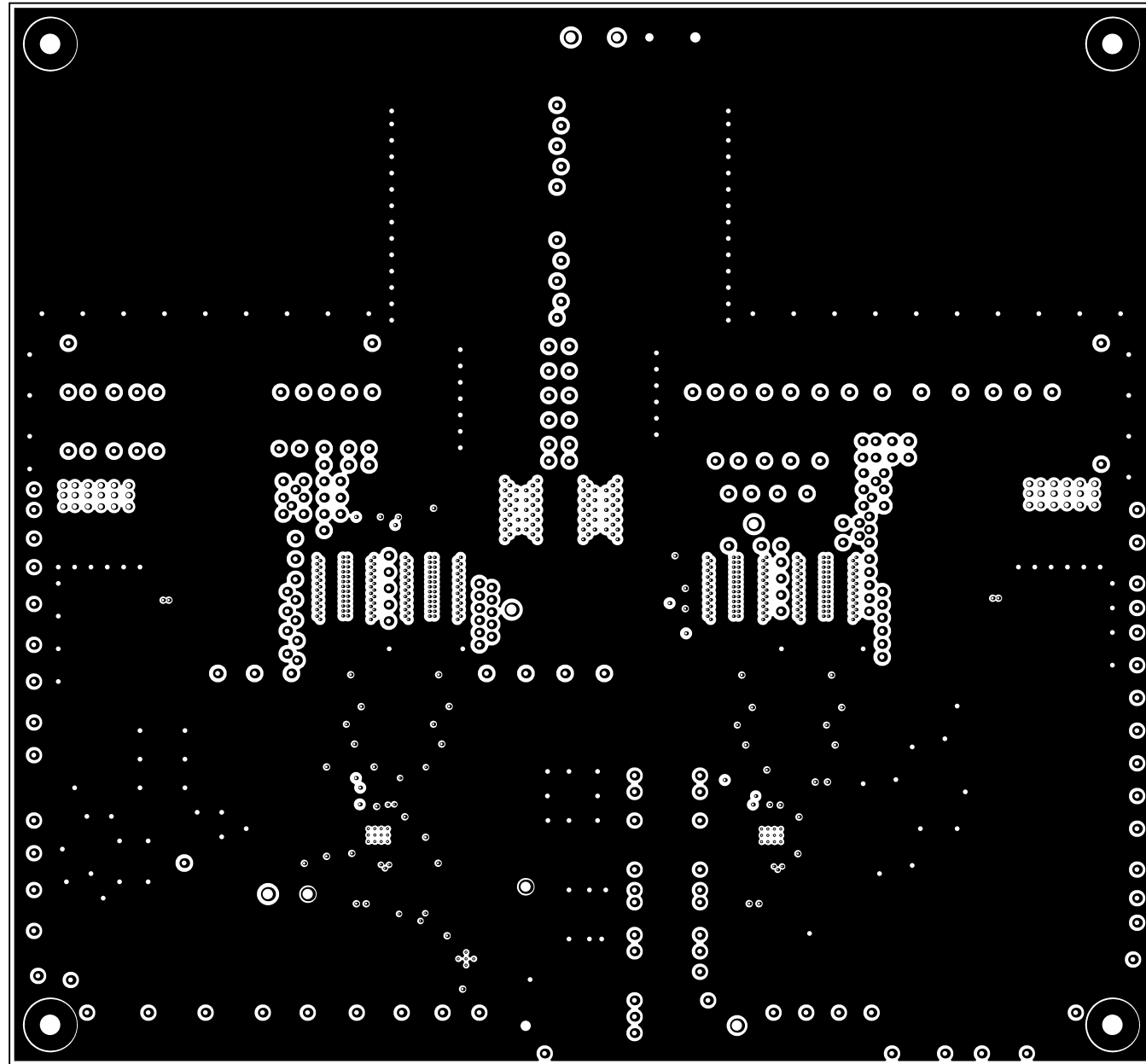
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Top Solder		
PLOT NAME = Top Solder Mask	GENERATED : 9/23/2015 2:04:18 PM	TEXAS INSTRUMENTS



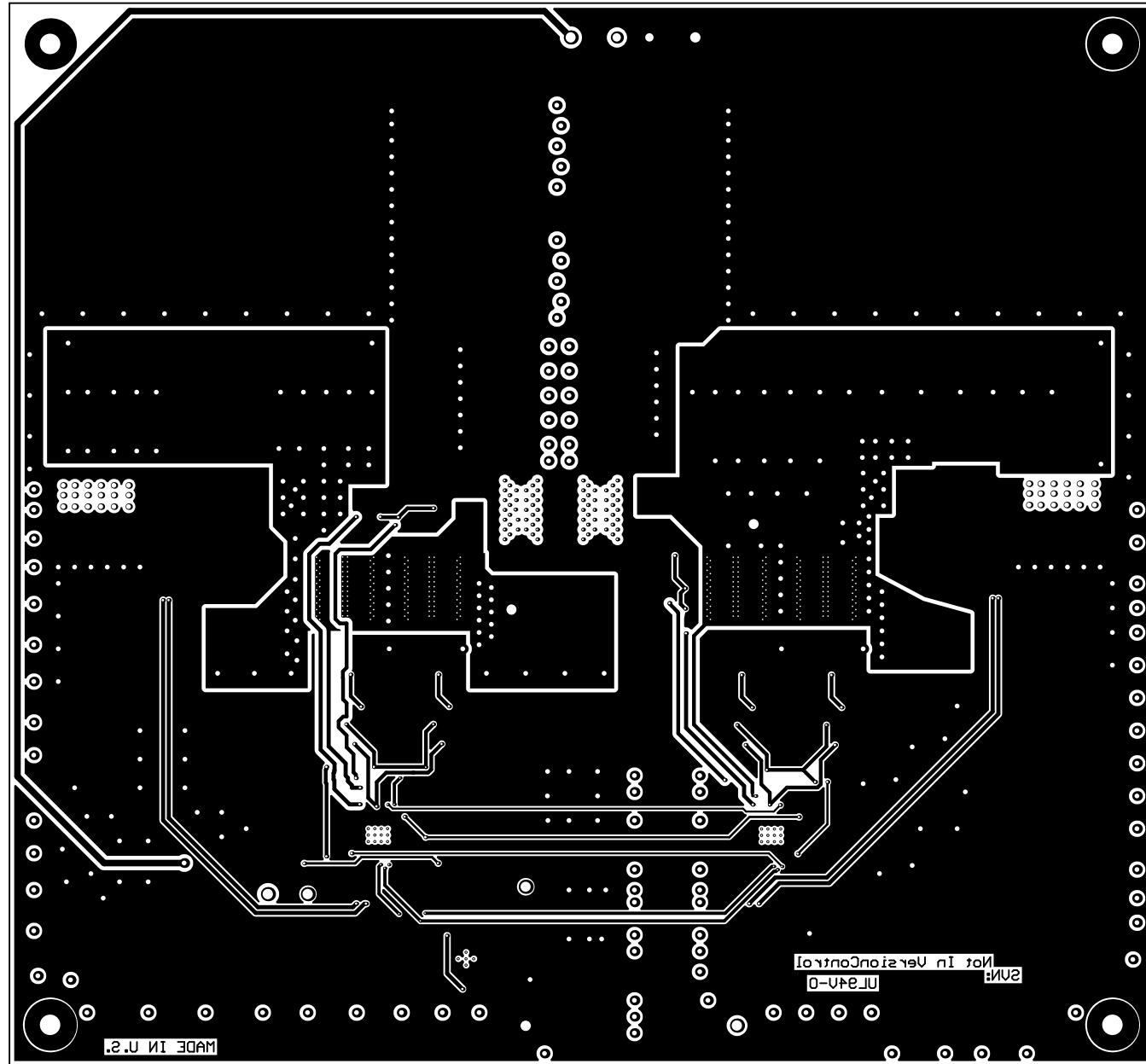
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Top Layer		
PLOT NAME = Top Layer	GENERATED : 9/23/2015 2:04:18 PM	TEXAS INSTRUMENTS



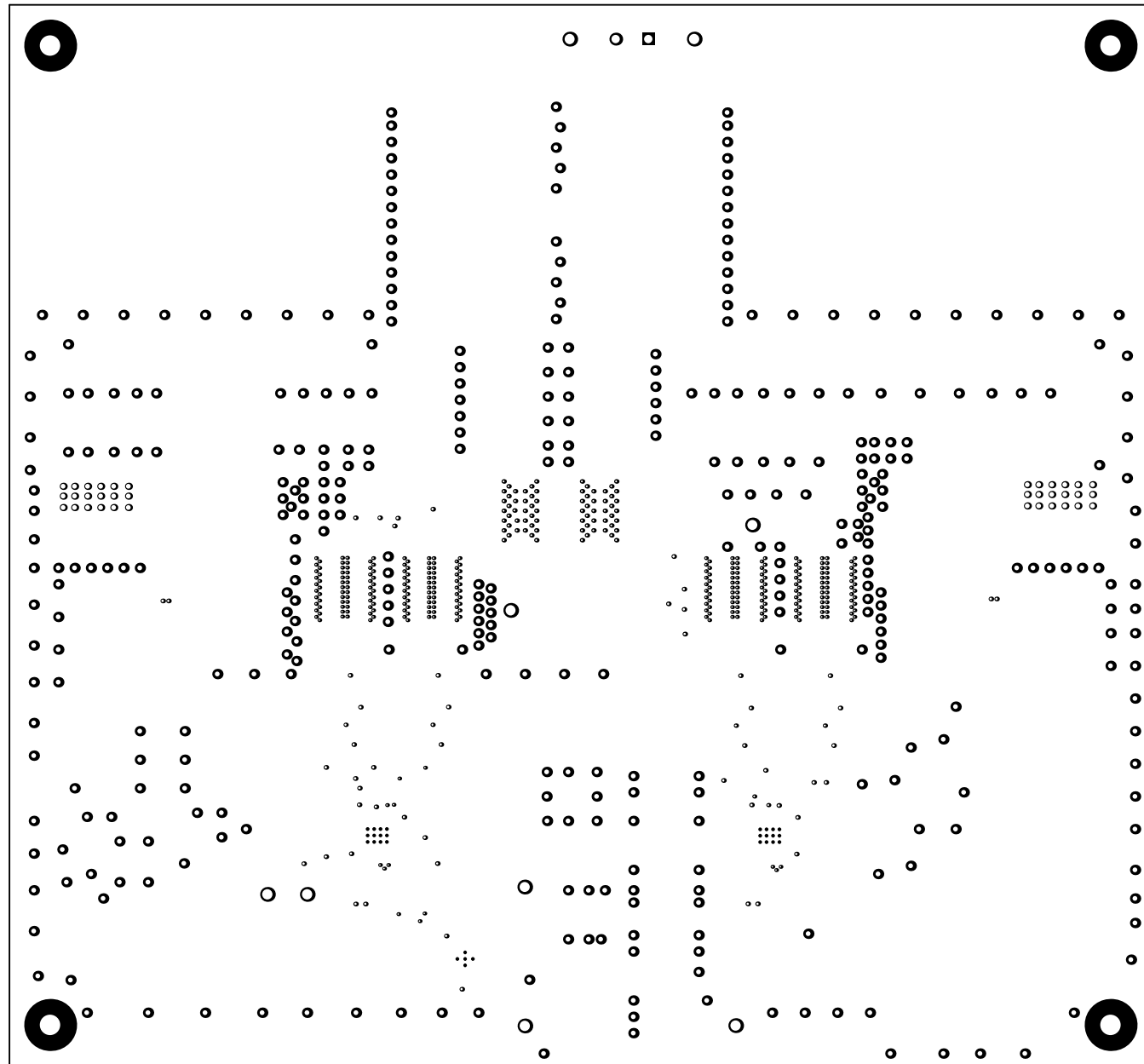
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME =		
PLOT NAME = Signal Layer 1	GENERATED : 9/23/2015 2:04:19 PM	TEXAS INSTRUMENTS



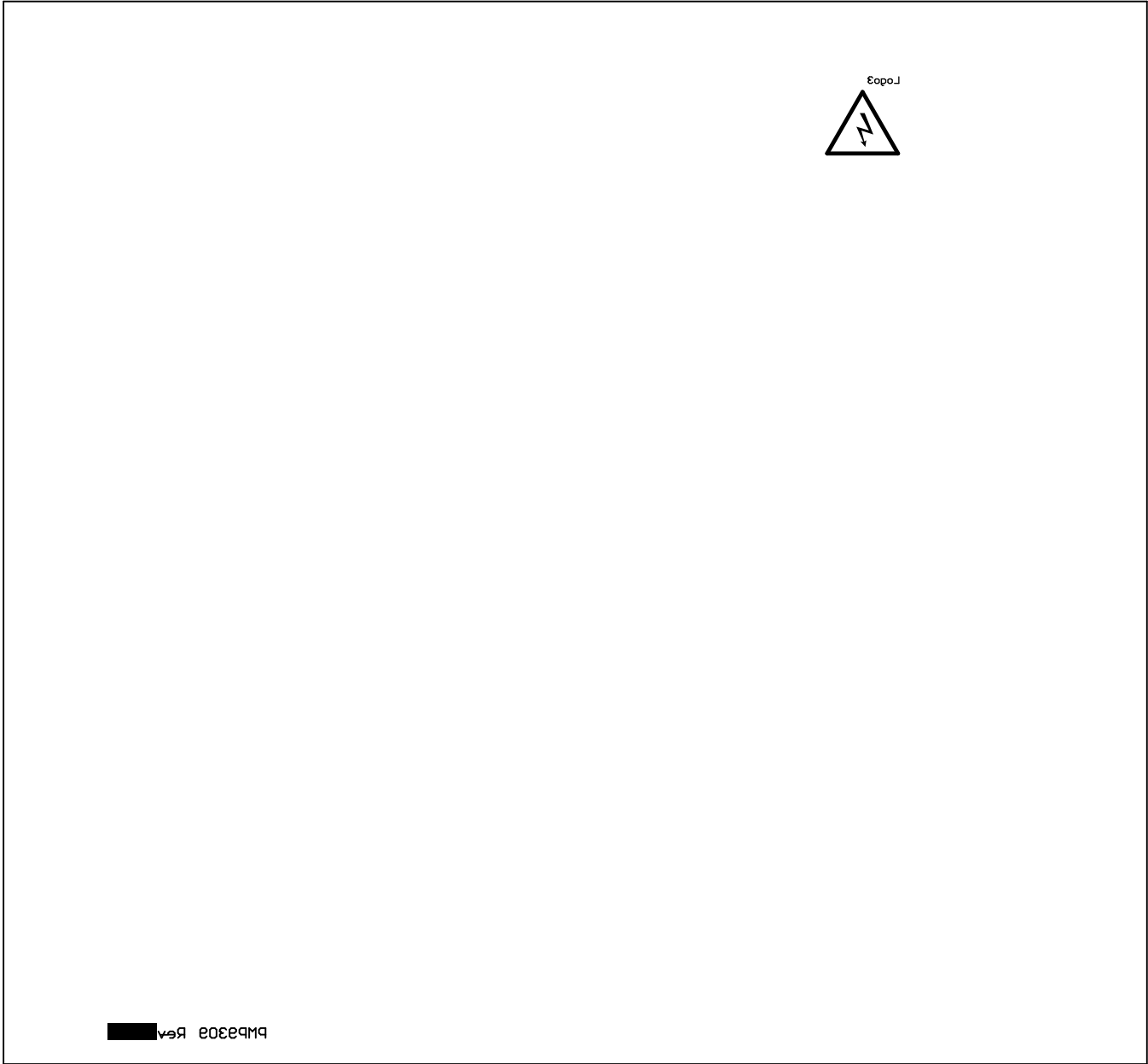
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME =		
PLOT NAME = Signal Layer 2	GENERATED : 9/23/2015 2:04:20 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Bottom Layer		
PLOT NAME = Bottom Layer	GENERATED : 9/23/2015 2:04:20 PM	TEXAS INSTRUMENTS

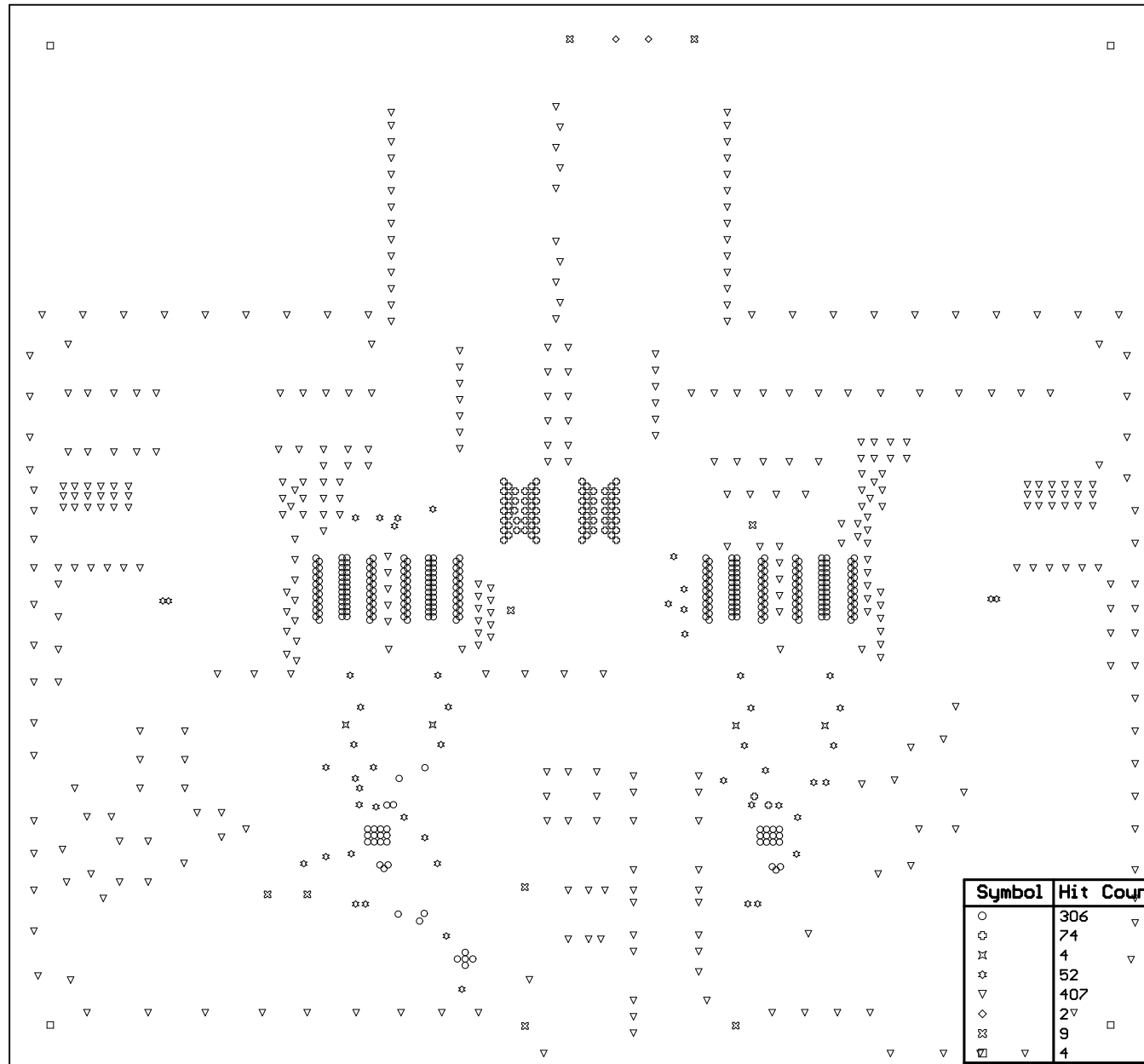


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Bottom Solder		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/23/2015 2:04:21 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN	REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/23/2015 2:04:21 PM	TEXAS INSTRUMENTS	

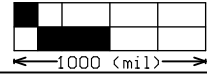
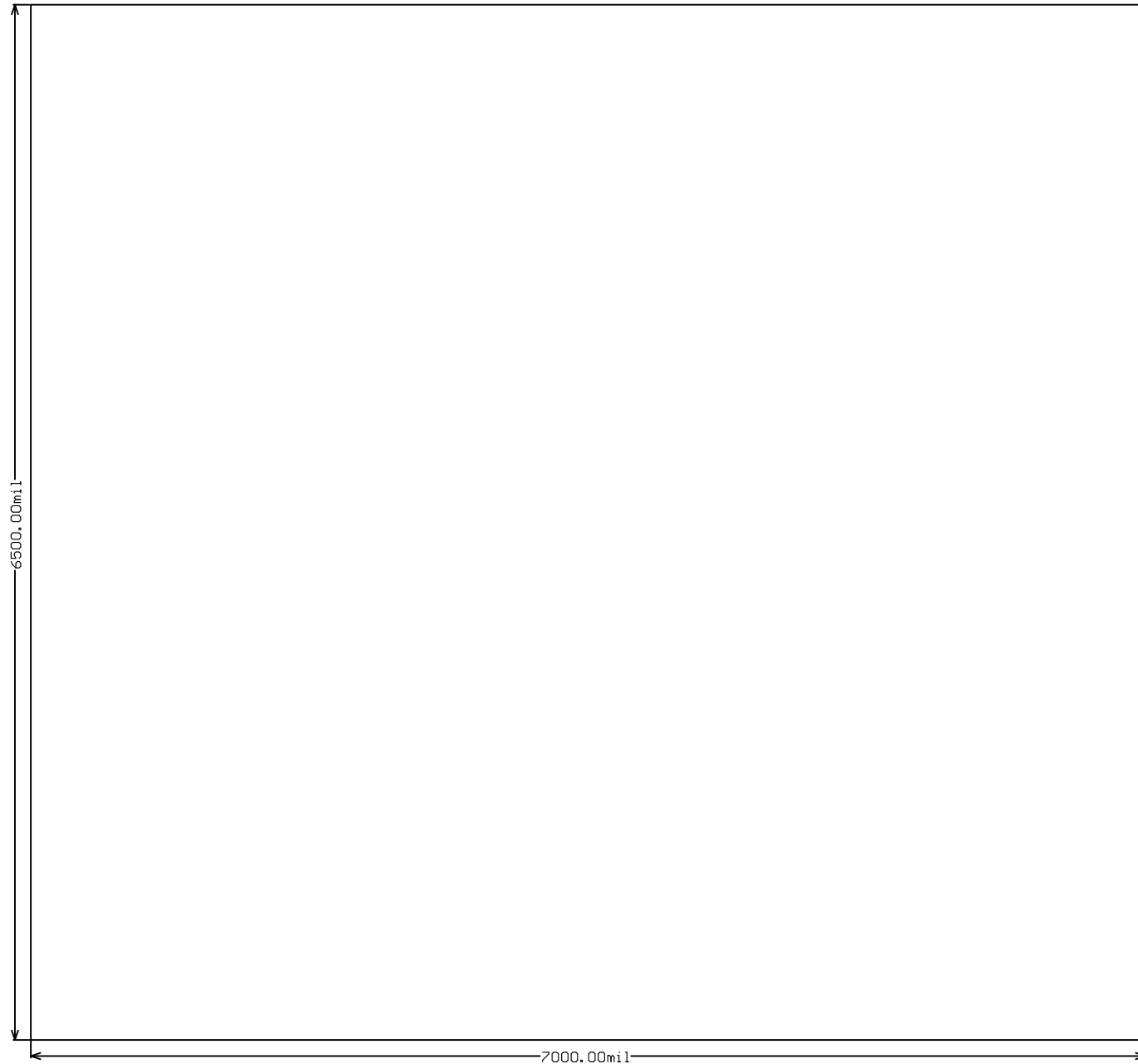




Symbol	Hit Count	Tool Size	Plated	Hole Type
○	306	10mil (0.254mm)	PTH	Round
◊	74	12mil (0.305mm)	PTH	Round
⊗	4	13mil (0.33mm)	PTH	Round
*	52	15mil (0.381mm)	PTH	Round
▽	407	30mil (0.762mm)	PTH	Round
◇	2	51.181mil (1.3mm)	PTH	Round
⊗	9	63mil (1.6mm)	PTH	Round
⊞	4	125.984mil (3.2mm)	PTH	Round
<b>858 Total</b>				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
LAYER NAME = Drill Drawing		
PLOT NAME = Drill Drawing	GENERATED : 9/23/2015 2:04:22 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN	REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/23/2015 2:04:23 PM	TEXAS INSTRUMENTS	

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